

Filename: PMP5291\_REVA\_bom.xls

Date: 01/18/2010

## PMP5291\_REVA BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
2	C1, C6	10uF	Capacitor, Ceramic, 16V, X7R, 20%	1206	GRM42-6yyyxxxKvv	muRata
4	C2, C3, C4, C5	0.1uF	Capacitor, Ceramic, 16V, X7R, 15%	0402	{Part Number}	{MFR}
2	D1, D3	Green	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	0603	160-1183-1-ND	Liteon
1	D2	Red	Diode, LED, Red, 1.8-V, 20-mA, 20-mcd	0603	160-1181-1-ND	Liteon
1	J1		Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35***	ED1609	OST
1	J2	D120/4DS	Terminal Block, 4-pin, 15-A, 5.1mm	0.80 x 0.35 inch	D120/4DS	OST
1	J3	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
see note L1, L2		4.7 uH	Inductor, Power, 0.58 A, ±20%	0.075 x 0.080 inch	XPL2010-472ML	Coilcraft
see note L3		10 uH	Inductor, SMT, yyA, zz-milliohm	0.126 X 0.126 inch	CDRH2D18B/HPNP-100M	Sumida
3	R1, R3, R8	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
3	R2, R4, R5	3.16k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R6	0.2	Resistor, Chip, 1/10W, 1%	0805	CRCW0805-xxxx-F	Vishay
1	R7	4.99k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	TP1, TP5	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP2, TP4, TP6	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	bq24120	IC, Advanced Li-Ion and Li-Pol Charge Management	RHL-20	bq24120RHL	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.
  5. Either L1 & L2 (2 parts) are populated or L3(one part) is populated

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